

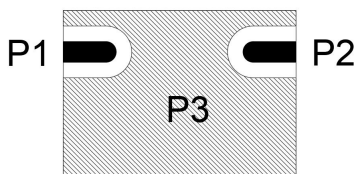
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

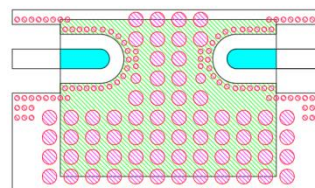
NO.	Parameter	SPEC
1	Frequency range	7610-7630 MHz
2	Insertion Loss	3.2dB max. at +25°C;
3	Ripple	0.5dB
4	Attenuation	60 dB min. @ DC-6000MHz 30 dB min. @ 9300MHz 50 dB min. @10000-16000MHz
5	VSWR (In BW)	2.0 max.
6	Port Impedance	50Ω
7	Power	0.5W max.
8	Operation Temperature Range	-55°C ~ +100°C




Construction



PIN	Connection
1	Input port
2	Output port
3	GND

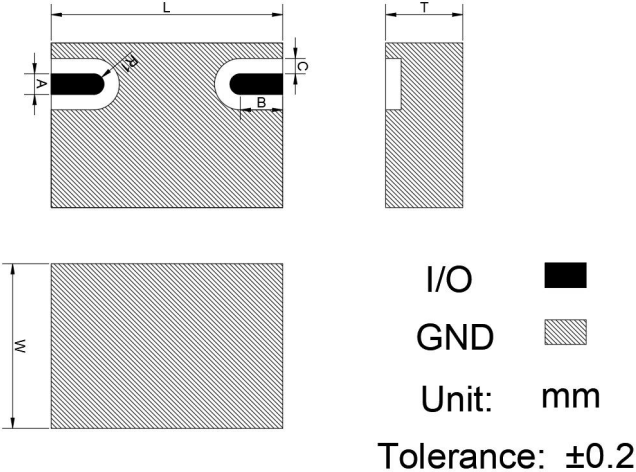
Mounting Considerations



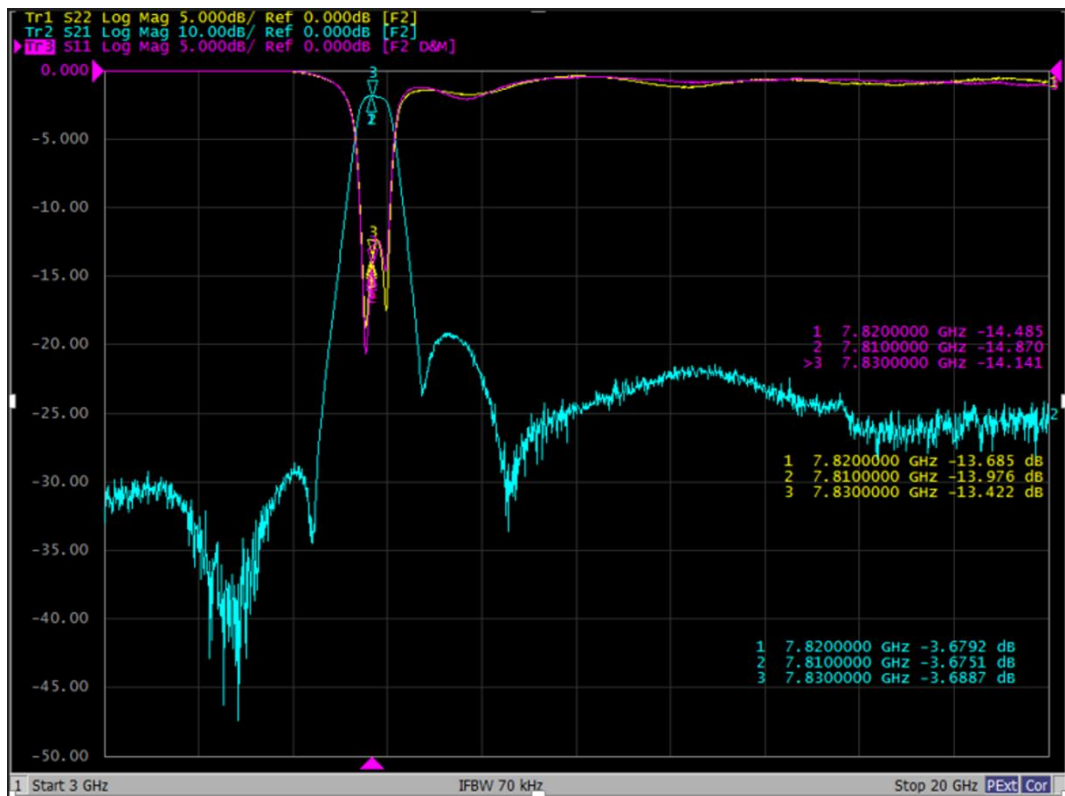
I/O 
 GND 
 Hole 

Unit: mm
 Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
 <p>Unit: mm Tolerance: ±0.2</p>	L	4.5 ± 0.20
	W	3.2 ± 0.20
	T	1.5 ± 0.20
	A	0.4 ± 0.10
	B	0.83 ± 0.10
	C	0.3 ± 0.10
	R1	0.2 ± 0.10

Typical Electrical Characteristics (T=25°C)



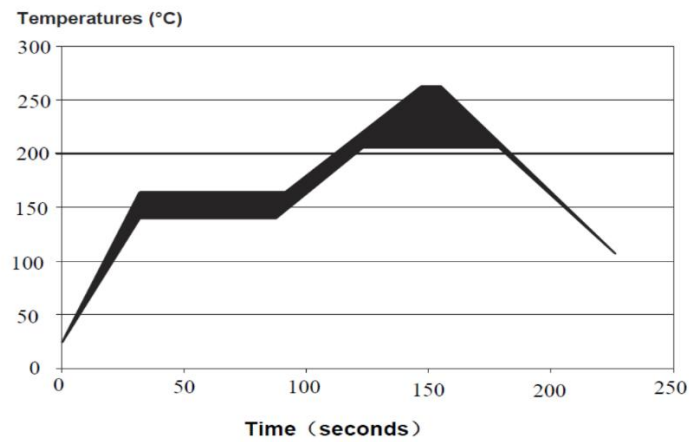
Yantel Corporation

Add: No.308-322,3F,Building 1,Juchuang Jingu Innovation Park,Wenyuan Road 35,Xili Street,Nanshan,Shenzhen,China

Tel: 86-755-8355-1886 Fax: 86-755-8355-2533

For detailed performance specs & shopping online see Yantel web site : www.yantel-corp.com

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.